



Material Content Data Sheet



Sales Product Name		PXFC192207NF V1 R500		Issued		27. September 2017		
MA#		MA001318352						
Package		PG-HBSOF-4-1		Weight*		3213.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	1.193	0.04		371	
	non noble metal	tin	7440-31-5	0.308	0.01		96	
	inorganic material	silicon	7440-21-3	9.014	0.28	0.33	2805	3272
leadframe	inorganic material	phosphorus	7723-14-0	0.142	0.00		44	
	non noble metal	zinc	7440-66-6	0.567	0.02		176	
	non noble metal	iron	7439-89-6	11.340	0.35		3529	
	non noble metal	copper	7440-50-8	460.434	14.33	14.70	143293	147042
wire	noble metal	gold	7440-57-5	21.879	0.68	0.68	6809	6809
encapsulation	organic material	carbon black	1333-86-4	2.950	0.09		918	
	plastics	epoxy resin	-	115.049	3.58		35805	
	inorganic material	silicondioxide	60676-86-0	865.328	26.93	30.60	269302	306025
leadfinish	non noble metal	nickel	7440-02-0	1.761	0.05		548	
	noble metal	palladium	7440-05-3	0.060	0.00		19	
	noble metal	gold	7440-57-5	0.097	0.00	0.05	30	597
plating	non noble metal	nickel	7440-02-0	1.996	0.06		621	
	noble metal	palladium	7440-05-3	0.068	0.00		21	
	noble metal	gold	7440-57-5	0.109	0.00	0.06	34	676
heatspreader	non noble metal	iron	7439-89-6	1.721	0.05		536	
	inorganic material	phosphorus	7723-14-0	0.516	0.02		161	
	non noble metal	copper	7440-50-8	1718.697	53.51	53.58	534882	535579
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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